

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM507954

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
PACIFIC WESTERN BANK		01/30/2019	STATE CHARTERED BANK: CALIFORNIA
RECEIVING PARTY DATA			
Name:	INNOVATIVE MICRO TECHNOLOGY, INC.		
Street Address:	75 ROBIN HILL ROAD		
City:	GOLETA		
State/Country:	CALIFORNIA		
Postal Code:	93117		
Entity Type:	Corporation: DELAWARE		
PROPERTY NUMBERS Total: 3			
Property Type	Number	Word Mark	
Registration Number:	3757243	CENFIRE	
Registration Number:	2770946	IMT	
Registration Number:	2673392	INNOVATIVE MICRO TECHNOLOGY	
CORRESPONDENCE DATA			
Fax Number:	9193541278		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>			
Phone:	(919) 314-3114		
Email:	diligencereview@square1bank.com		
Correspondent Name:	PACIFIC WESTERN BANK		
Address Line 1:	406 BLACKWELL STREET		
Address Line 2:	SUITE 240		
Address Line 4:	DURHAM, NORTH CAROLINA 27701		
NAME OF SUBMITTER:	NICHOLAS NANCE		
SIGNATURE:	/NICHOLAS NANCE-JLT/		
DATE SIGNED:	01/30/2019		
Total Attachments: 6			
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RELEASE OF SECURITY INTEREST

This Release of Security Interest is made as of January 30, 2019, by **PACIFIC WESTERN BANK**, a California state chartered bank ("Bank"), in favor of **INNOVATIVE MICRO TECHNOLOGY, INC.**, a Delaware corporation ("Grantor"), with its principal place of business located at 75 Robin Hill Road, Goleta, California 93117.

Recitals

WHEREAS Grantor granted to Bank a security interest in its copyrights, patents and trademarks, including without limitation its patents and trademarks described on Exhibits A and B attached hereto (respectively) (collectively, the "Intellectual Property"), under that certain Intellectual Property Security Agreement dated as of November 28, 2017 (as amended from time to time, the "Security Agreement"), and recorded with the United States Patent and Trademark Office as set forth on Exhibits A and B.


WHEREAS Bank agrees to release its security interest in the Intellectual Property.

Agreement

Now therefore, Bank agrees that it terminates and releases its security interest in the Intellectual Property and reassigns to Grantor, without warranty or recourse, all interest of Bank in the Intellectual Property.

BANK:

PACIFIC WESTERN BANK


Name: John Weston
Title: SVP

406 Blackwell Street
Suite 240
Durham, NC 27701

EXHIBIT A
Patents

Bank's security interest in the following patents was recorded at the United States Patent and Trademark Office on November 30, 2017 at Reel and Frame Number 044553/0257:

<u>Description</u>	<u>Issued Patent / Patent Application Number</u>	<u>Issued Patent / Patent Application Date</u>
Method and apparatus for assembling an array of micro-devices	6812061	11/2/04
Method and apparatus for assembling an array of micro-devices	7057245	6/6/06
Method and apparatus for assembling an array of micro-devices	7141080	11/28/06
Mems teeter-totter apparatus with curved beam and method of manufacture	7210352	5/1/07
Mems particle sorting actuator and method of manufacturing	9372185	6/21/16
Trench plating process and apparatus for through hole vias	7233048	6/19/07
Multiple switch mems structure and method of manufacture	7276991	10/2/07
Indented structure for encapsulated devices and method of manufacture	7462931	12/9/08
Dual substrate electrostatic mems switch with hermetic seal and method of manufacture	7528691	5/5/09
Elastic interface for wafer bonding apparatus	7533792	5/19/09
Hysteretic mems thermal device and method of manufacture	7548145	6/16/09
System and method for providing access to an encapsulated device	7550778	6/23/09
Wafer level hermetic bond using metal alloy with raised feature	7569926	8/4/09

Hermetic interconnect structure and method of manufacture	7582969	9/1/09
Mems thermal actuator and method of manufacture	7622783	11/24/09
Hysteretic mems two-dimensional thermal device and method of manufacture	7626311	12/1/09
Interconnect structure using through wafer vias and method of fabrication	7675162	3/9/10
Current-driven device using nimn alloy and method of manufacture	7687304	3/30/10
Contact electrode for microdevices and etch method of manufacture	7688167	3/30/10
Etching/bonding chamber for encapsulated devices and method of use	7713786	5/11/10
Singly attached mems thermal device and method of manufacture	7724121	5/25/10
Mems thermal actuator and method of manufacture	7759152	7/20/10
Indented lid for encapsulated devices and method of manufacture	7759218	7/20/10
System and method for forming moveable features on a composite substrate	7785913	8/31/10
Wafer bonding material with embedded rigid particles	7807547	10/5/10
Mems device using nimn alloy and method of manufacture	7812703	10/12/10
Mems plate switch and method of manufacture	7864006	1/4/11
Mems thermal device with slideably engaged tether and method of manufacture	7872432	1/18/11
Dual substrate mems plate switch and method of manufacture	7893798	2/22/11
Hysteretic mems thermal device and method of manufacture	7944113	5/17/11
Wafer level hermetic bond using metal alloy with raised feature	7960208	6/14/11

Lid structure for microdevice and method of manufacture	7968986	6/28/11
Wafer bonding material with embedded conductive particles	7972683	7/5/11
System and method for providing access to an encapsulated device	8088651	1/3/12
Method of manufacturing a hysteretic mems two-dimensional thermal device	8245391	8/21/12
Dual substrate mems plate switch and method of manufacture	8264307	9/11/12
Wafer level hermetic bond using metal alloy with keeper layer	8288211	10/16/12
Method and apparatus for applying thin liquid coatings	8338283	12/25/12
Plating process and apparatus for through wafer features	8343791	1/1/13
Configurable power supply using MEMS switch	8466760	6/18/13
Inlaid optical material and method of manufacture	8541735	9/24/13
Inductive getter activation for high vacuum packaging	8558364	10/15/13
Microfabricated electromagnetic actuator with push-pull motion	8608700	12/17/13
In-plane electromagnetic MEMS pump	8690830	4/8/14
Wafer level hermetic bond using metal alloy with keeper layer	8736081	5/27/14
Cartridge for MEMS particle sorting system <i>*Co-owned with Owl Biomedical, Inc.</i>	8822207	9/2/14
Exothermic activation for high vacuum packaging	8847373	9/30/14
MEMS particle sorting actuator and method of manufacturing	8871500	10/28/14
Multi-stage cartridge for MEMS particle storing system <i>*Co-owned with Owl Biomedical, Inc.</i>	8993311	3/31/15
Method and device using silicon substrate to glass substrate anodic bonding	9156679	10/13/15

Microfabricated magnetic field transducer with flux guide	9274180	3/1/16
Method for forming a microfabricated structure	9302905	4/5/16
Method using glass substrate anodic bonding	9315375	4/19/16
Device using glass substrate anodic bonding	9388037	7/12/16
Wafer level hermetic bond using metal alloy with raised feature and wetting layer	9162878	10/20/15
Solder bump sealing method and device	9330874	5/3/16
Method for forming through substrate vias with tethers	9324613	4/26/16
Etching technique for microfabrication substrates	9493877	11/15/16
Anodic bonding of dielectric substrates	9533877	1/3/17
Microfabricated optical apparatus	9608731	3/28/17
Thermocompression bonding with raised feature	15/634230	11/2/17
Dual substrate electrostatic mems switch with multiple hinges and method of manufacture	15/060630	3/4/16
Thermocompression bonding with raised feature	15/149217	5/9/16
Mems reed switch device	15/237120	8/15/16
Device with separation limiting standoff	15/232871	8/10/16
Microfabricated optical apparatus	15/408956	1/18/17
Microfabricated optical apparatus with integrated turning surface	15/355461	11/18/16
Through substrate vias using solder bumps	15/415919	1/26/17
Microfabricated optical apparatus	15/272481	9/22/16

EXHIBIT B
Trademarks

Bank's security interest in the following trademarks was recorded at the United States Patent and Trademark Office on November 30, 2017 at Reel and Frame Number 044553/0257:

<u>Description</u>	<u>Registration Number</u>	<u>Registration Date</u>
Cenfire	3757243	3/9/10
IMT	2770946	10/7/03
INNOVATIVE MICRO TECHNOLOGY	2673392	1/7/03